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Irish Standard  
I.S. EN 60297-3-107:2012

Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series -- Part 3-107: Dimensions of subracks and plug-in units, small form factor (IEC 60297-3-107:2012 (EQV))

## I.S. EN 60297-3-107:2012

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EUROPEAN STANDARD  
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English version

**Mechanical structures for electronic equipment -  
Dimensions of mechanical structures of the 482,6 mm (19 in) series -  
Part 3-107: Dimensions of subracks and plug-in units, small form factor  
(IEC 60297-3-107:2012)**

Structures mécaniques pour équipements  
électroniques -  
Dimensions des structures mécaniques de  
la série 482,6 mm (19 pouces) -  
Partie 3-107: Dimensions des bacs et  
blocs enfichables de petit facteur de forme  
(CEI 60297-3-107:2012)

Bauweisen für elektronische  
Einrichtungen -  
Maße der 482,6 mm-(19-Zoll-)Bauweise -  
Teil 3-107: Maße von Baugruppenträgern  
und Baugruppen, kleiner Formfaktor  
(IEC 60297-3-107:2012)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

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**I.S. EN 60297-3-107:2012**

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**Foreword**

The text of document 48D/492/FDIS, future edition 1 of IEC 60297-3-107, prepared by SC 48D, "Mechanical structures for electronic equipment", of IEC TC 48, "Electromechanical components and mechanical structures for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60297-3-107:2012.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2012-11-14
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2015-02-14

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60297-3-100	-	Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series - Part 3-100: Basic dimensions of front panels, subracks, chassis, racks and cabinets	EN 60297-3-100	-
IEC 61076-4-116	-	Connectors for electronic equipment - Product EN 61076-4-116 requirements - Part 4-116: Printed board connectors - Detail specification for a high-speed two-part connector with integrated shielding function	EN 61076-4-116	-
PICMG AMC.0	-	Advanced Mezzanine Card Specification	-	-
PICMG MicroTCA.0	-	Micro Telecommunications Computing Architecture	-	-
PICMG MicroTCA.1	-	Air Cooled Rugged MicroTCA Specification	-	-

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

# MECHANICAL STRUCTURES FOR ELECTRONIC EQUIPMENT – DIMENSIONS OF MECHANICAL STRUCTURES OF THE 482,6 mm (19 in) SERIES –

## Part 3-107: Dimensions of subracks and plug-in units, small form factor

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60297-3-107 has been prepared by subcommittee 48D: Mechanical structures for electronic equipment, of IEC technical committee 48: Electromechanical components and mechanical structures for electronic equipment.

The text of this standard is based on the following documents:

FDIS	Report on voting
48D/492/FDIS	48D/501/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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A list of all parts of IEC 60297 series, under the general title *Mechanical structures for electronic equipment – Dimensions of mechanical structures of the 482,6 mm (19 in) series*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

## INTRODUCTION

This standard provides for an alternative/smaller form factor of plug-in units as defined in IEC 60297-3-101.

New technologies requiring smaller plug-in unit form factors used in 19 in equipment practice are rapidly gaining acceptance.

Recognizing this development it became obvious that a generic interface standard would be an advantage to the industry.

This standard is based upon and coordinated with the plug-in unit form factor as defined in AMC.0 and MicroTCA developed by PICMG (PCI Industrial Computers Manufacturer Group).

By making critical interface dimensions available and permitting the use of alternative connectors to the industry (beyond AMC.0 and MicroTCA) multiple product solutions may make use of this technology and will increase the overall market acceptance, increase availability, and reduce cost.

In order to meet the requirements of small form factor plug-in units within the subrack the interface dimensions required differ from IEC 60297-3-101. This standard defines these small form factor interface dimensions.

The small form factor generic dimensions are based on and coordinated with AMC.0 and MicroTCA.

Since the AMC.0 and MicroTCA Specification defines only a limited range of connectors this standard opens the possible use of other suitable connectors.

## **MECHANICAL STRUCTURES FOR ELECTRONIC EQUIPMENT – DIMENSIONS OF MECHANICAL STRUCTURES OF THE 482,6 mm (19 in) SERIES –**

### **Part 3-107: Dimensions of subracks and plug-in units, small form factor**

#### **1 Scope and object**

This part of IEC 60297 defines the interface dimensions between subracks and associated plug-in units using connectors as defined in PICMG-MTCA.0 (Fixed board, see Figure 7) and IEC 61076-4-116 (Two part, see Figure 12) and other two part connectors, (see Figure 15).

For mechanical and climatic tests refer to IEC 61587-1.

For electromagnetic shielding performance tests refer to IEC 61587-3.

#### **2 Normative references**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60297-3-100: *Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series – Part 3-100: Basic dimensions of front panels, subracks, chassis, racks and cabinets*

IEC 61076-4-116: *Connectors for electronic equipment – Product requirements – Printed board connectors: Detail specification for a high-speed two-part connector with integrated shielding function* (to be published)

PICMG AMC.0: *Advanced Mezzanine Card Specification*

PICMG MicroTCA.0: *Micro Telecommunications Computing Architecture*

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